



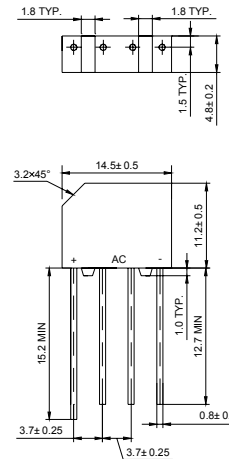
VOLTAGE RANGE: 50 --- 1000 V

CURRENT: 2.0 A

KBP

Features

- ◇ Rating to 1000V PRV
- ◇ Surge overload rating to 50 Amperes peak
- ◇ Ideal for printed circuit board
- ◇ Reliable low cost construction utilizing molded plastic technique results in inexpensive product
- ◇ Lead solderable per MIL-STD-202 method 208
- ◇ Plastic material has UL flammability classification 94V-0
- ◇ Weight: 0.050 ounces, 1.42 grams
- ◇ Glass passivated chip junctions



Dimensions in millimeters

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

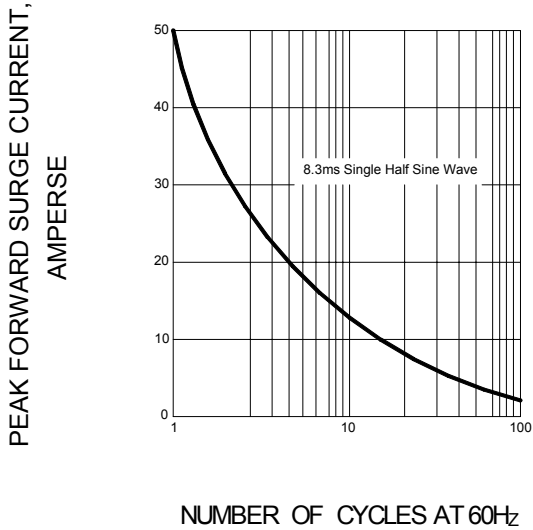
Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate by 20%.

		KBP 2005	KBP 201	KBP 202	KBP 204	KBP 206	KBP 208	KBP 210	UNITS
Maximum recurrent peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward Output current @ $T_A=25^\circ\text{C}$	$I_{F(AV)}$	2.0							A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load	I_{FSM}	50.0							A
I^2t Rating for fusing @ $T_j=25^\circ\text{C}$	I^2t	10.4							A ² S
Maximum instantaneous forward voltage @ 2.0 A	V_F	1.1							V
Maximum reverse current @ $T_A=25^\circ\text{C}$ at rated DC blocking voltage @ $T_A=100^\circ\text{C}$	I_R	10.0 1.0							μA mA
Typical Thermal Resistance (Note)	$R_{\theta JA}$ $R_{\theta JC}$ $R_{\theta JL}$	25 5 8							$^\circ\text{C/W}$
Operating junction temperature range	T_J	- 55 ---- + 150							$^\circ\text{C}$
Storage temperature range	T_{STG}	- 55 ---- + 150							$^\circ\text{C}$

Ratings AND Characteristic Curves

FIG.1 – PEAK FORWARD SURGE CURRENT



**FIG.2 – FORWARD DERATING CURVE
OUTPUT RECTIFIED CURRENT**

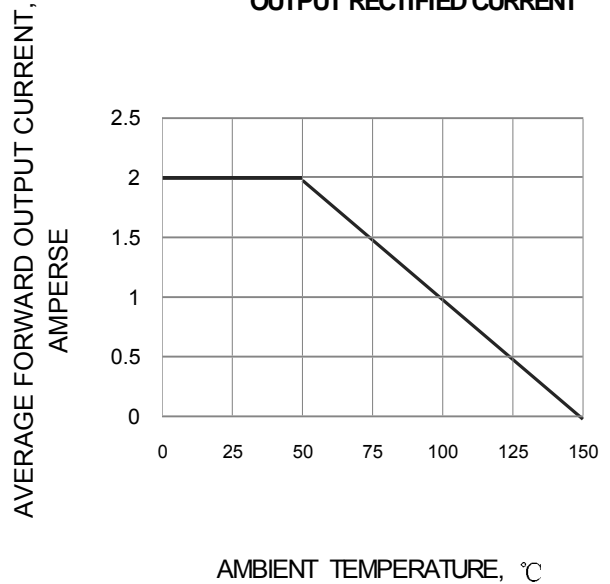


FIG.3 – TYPICAL FORWARD CHARACTERISTIC

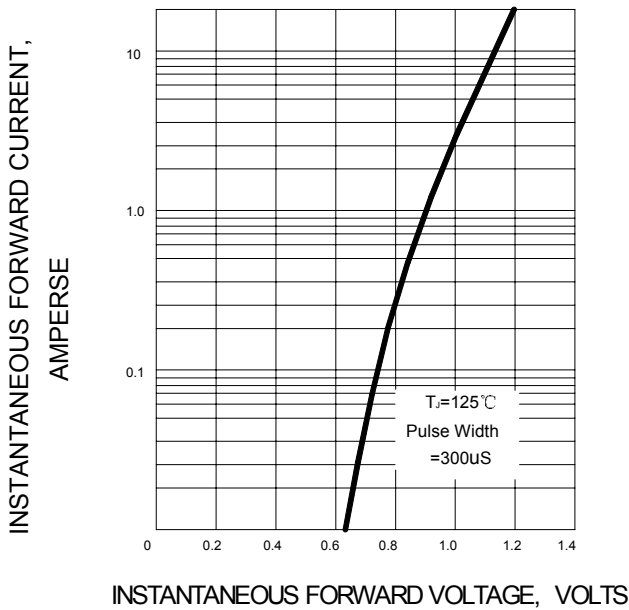


FIG.4 – TYPICAL REVERSE CHARACTERISTIC

